

E Series Power MOSFET

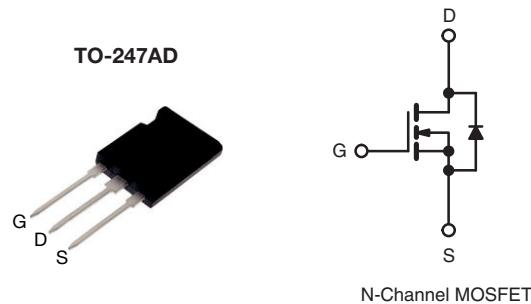
PRODUCT SUMMARY	
V_{DS} (V) at T_J max.	650
$R_{DS(on)}$ max. at 25 °C (Ω)	$V_{GS} = 10$ V 0.158
Q_g max. (nC)	95
Q_{gs} (nC)	16
Q_{gd} (nC)	25
Configuration	Single

FEATURES

- Low Figure-of-Merit (FOM) $R_{on} \times Q_g$
- Low Input Capacitance (C_{iss})
- Reduced Switching and Conduction Losses
- Ultra Low Gate Charge (Q_g)
- Avalanche Energy Rated (UIS)
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE



APPLICATIONS

- Server and Telecom Power Supplies
- Switch Mode Power Supplies (SMPS)
- Power Factor Correction Power Supplies (PFC)
- Lighting
 - High-Intensity Discharge (HID)
 - Fluorescent Ballast Lighting
- Industrial
 - Welding
 - Induction Heating
 - Motor Drives
 - Battery Chargers
 - Renewable Energy
 - Solar (PV Inverters)

ORDERING INFORMATION	
Package	TO-247AD
Lead (Pb)-free and Halogen-free	SiHW23N60E-GE3

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V_{DS}	600	V
Gate-Source Voltage		V_{GS}	± 20	
Gate-Source Voltage AC ($f > 1$ Hz)			30	
Continuous Drain Current ($T_J = 150$ °C)	V_{GS} at 10 V	I_D	23	A
	$T_C = 25$ °C		15	
Pulsed Drain Current ^a		I_{DM}	63	
Linear Derating Factor			1.8	W/°C
Single Pulse Avalanche Energy ^b		E_{AS}	353	mJ
Maximum Power Dissipation		P_D	227	W
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to + 150	°C
Drain-Source Voltage Slope	$T_J = 125$ °C	dV/dt	37	V/ns
Reverse Diode dV/dt			34	
Soldering Recommendations (Peak Temperature) ^c	for 10 s		300	°C

Notes

- Repetitive rating; pulse width limited by maximum junction temperature.
- $V_{DD} = 50$ V, starting $T_J = 25$ °C, $L = 28.2$ mH, $R_g = 25$ Ω, $I_{AS} = 5$ A.
- 1.6 mm from case.
- $I_{SD} \leq I_D$, $dI/dt = 100$ A/μs, starting $T_J = 25$ °C.

THERMAL RESISTANCE RATINGS

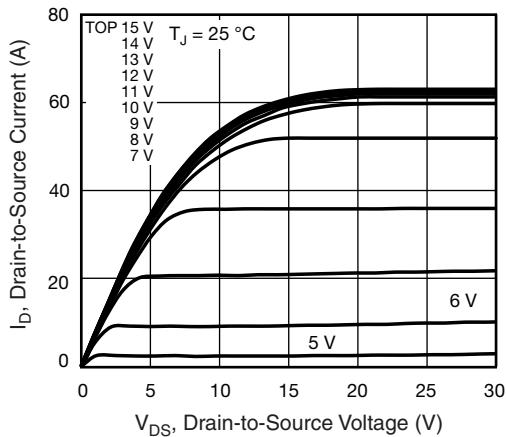
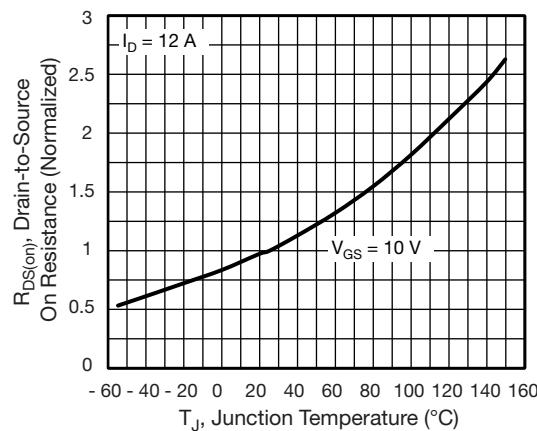
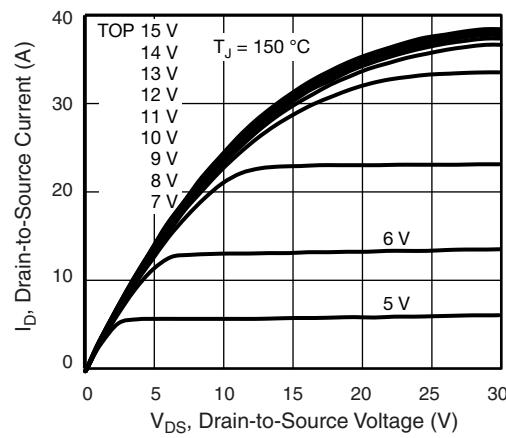
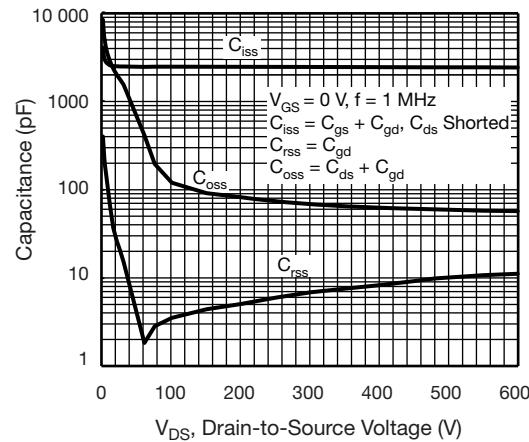
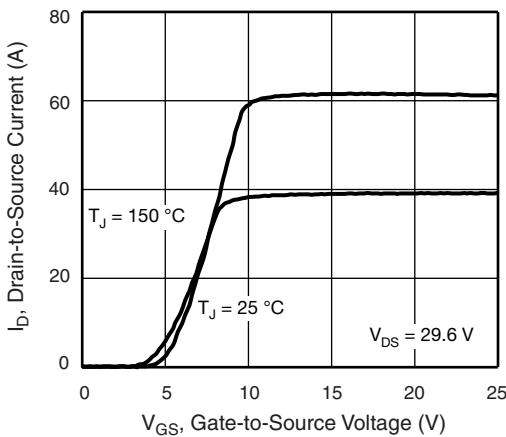
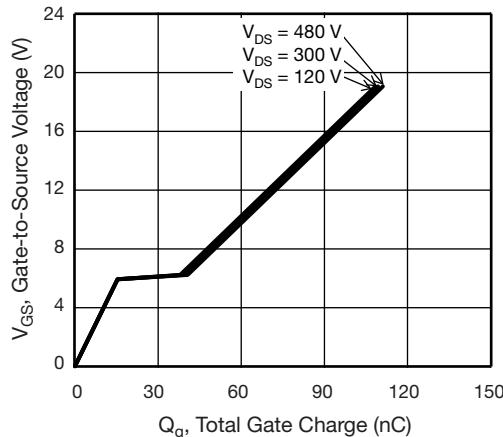
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	40	$^{\circ}\text{C}/\text{W}$
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.55	

SPECIFICATIONS ($T_J = 25^{\circ}\text{C}$, unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static								
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}$	$I_D = 250 \mu\text{A}$	600	-	-	V	
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25°C , $I_D = 1 \text{ mA}$		-	0.72	-	$^{\circ}\text{C}/\text{V}$	
Gate-Source Threshold Voltage (N)	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$		2	-	4	V	
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 600 \text{ V}$, $V_{GS} = 0 \text{ V}$		-	-	1	μA	
		$V_{DS} = 480 \text{ V}$, $V_{GS} = 0 \text{ V}$, $T_J = 125^{\circ}\text{C}$		-	-	10		
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$	$I_D = 12 \text{ A}$	-	0.132	0.158	Ω	
Forward Transconductance	g_{fs}	$V_{DS} = 30 \text{ V}$, $I_D = 12 \text{ A}$		-	6.4	-	S	
Dynamic								
Input Capacitance	C_{iss}	$V_{GS} = 0 \text{ V}$, $V_{DS} = 100 \text{ V}$, $f = 1 \text{ MHz}$		-	2418	-	pF	
Output Capacitance	C_{oss}			-	119	-		
Reverse Transfer Capacitance	C_{rss}			-	4	-		
Effective Output Capacitance, Energy Related ^a	$C_{o(er)}$	$V_{DS} = 0 \text{ V}$ to 480 V , $V_{GS} = 0 \text{ V}$		-	107	-	pF	
Effective Output Capacitance, Time Related ^b	$C_{o(tr)}$			-	320	-		
Total Gate Charge	Q_g	$V_{GS} = 10 \text{ V}$	$I_D = 12 \text{ A}$, $V_{DS} = 480 \text{ V}$	-	63	95	nC	
Gate-Source Charge	Q_{gs}			-	16	-		
Gate-Drain Charge	Q_{gd}			-	25	-		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 480 \text{ V}$, $I_D = 12 \text{ A}$, $V_{GS} = 10 \text{ V}$, $R_g = 9.1 \Omega$		-	22	44	ns	
Rise Time	t_r			-	38	76		
Turn-Off Delay Time	$t_{d(off)}$			-	66	99		
Fall Time	t_f			-	34	68		
Gate Input Resistance	R_g	$f = 1 \text{ MHz}$, open drain		-	0.73	-	Ω	
Drain-Source Body Diode Characteristics								
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	23	A	
Pulsed Diode Forward Current	I_{SM}			-	-	63		
Diode Forward Voltage	V_{SD}	$T_J = 25^{\circ}\text{C}$, $I_S = 12 \text{ A}$, $V_{GS} = 0 \text{ V}$		-	0.9	1.2	V	
Reverse Recovery Time	t_{rr}	$T_J = 25^{\circ}\text{C}$, $I_F = I_S = 12 \text{ A}$, $dI/dt = 100 \text{ A}/\mu\text{s}$, $V_R = 25 \text{ V}$		-	384	768	ns	
Reverse Recovery Charge	Q_{rr}			-	6.4	12.8		
Reverse Recovery Current	I_{RRM}			-	30	-	A	

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .
b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Fig. 1 - Typical Output Characteristics

Fig. 4 - Normalized On-Resistance vs. Temperature

Fig. 2 - Typical Output Characteristics

Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

Fig. 3 - Typical Transfer Characteristics

Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

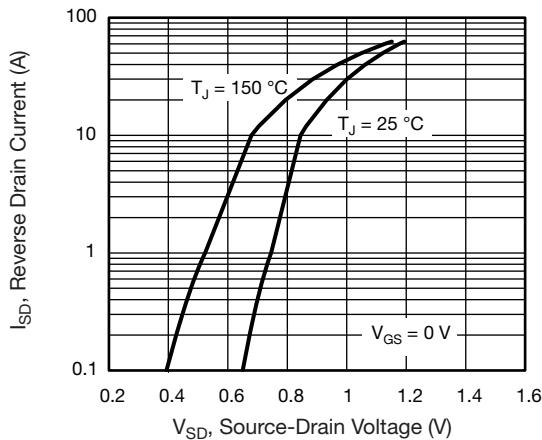


Fig. 7 - Typical Source-Drain Diode Forward Voltage

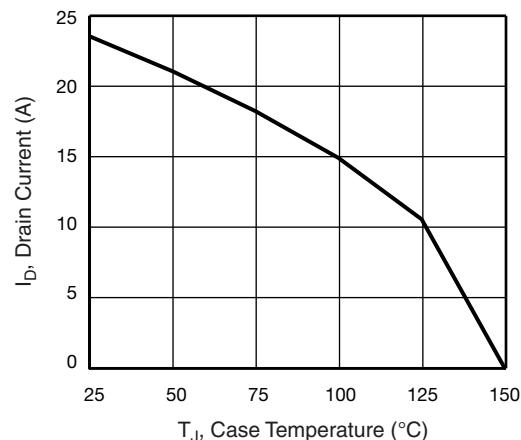


Fig. 9 - Maximum Drain Current vs. Case Temperature

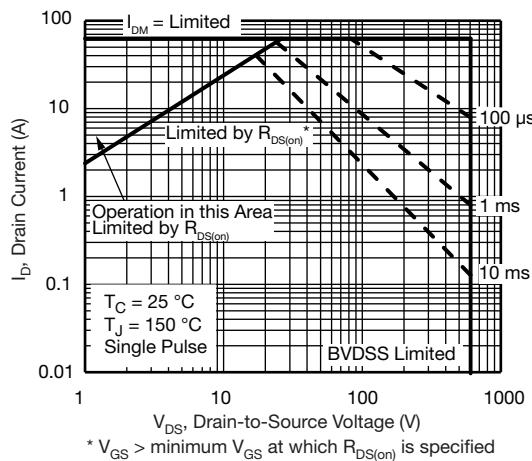


Fig. 8 - Maximum Safe Operating Area

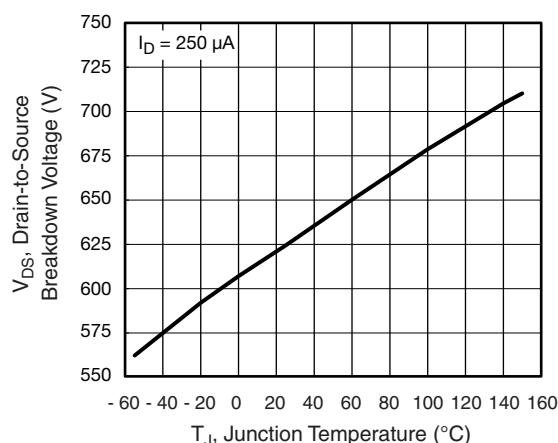


Fig. 10 - Temperature vs. Drain-to-Source Voltage

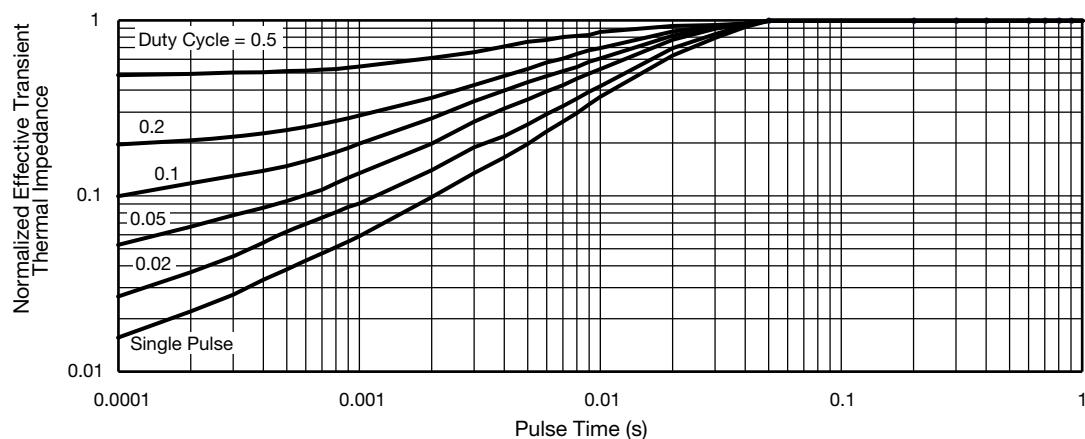


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case

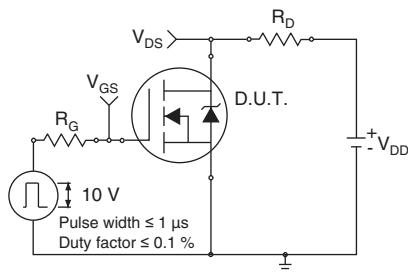


Fig. 12 - Switching Time Test Circuit

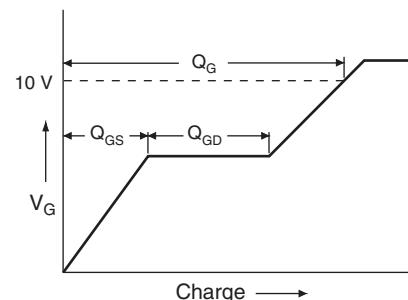


Fig. 16 - Basic Gate Charge Waveform

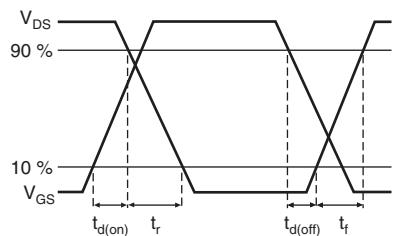


Fig. 13 - Switching Time Waveforms

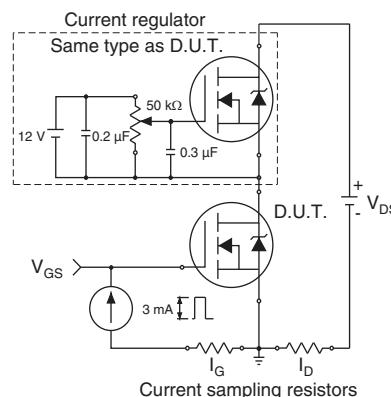


Fig. 17 - Gate Charge Test Circuit

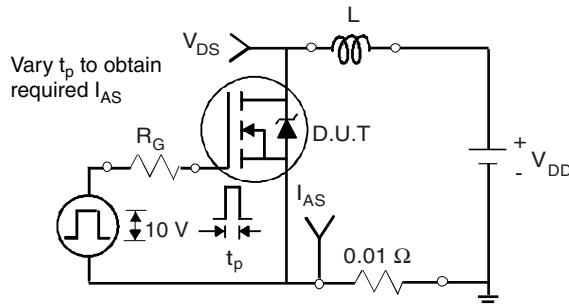


Fig. 14 - Unclamped Inductive Test Circuit

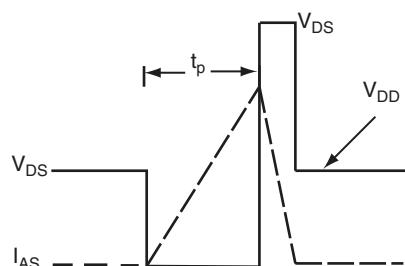
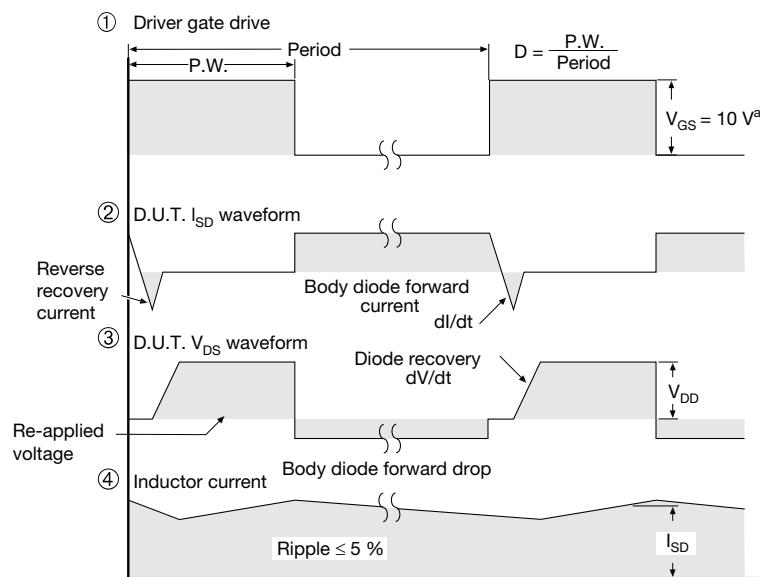
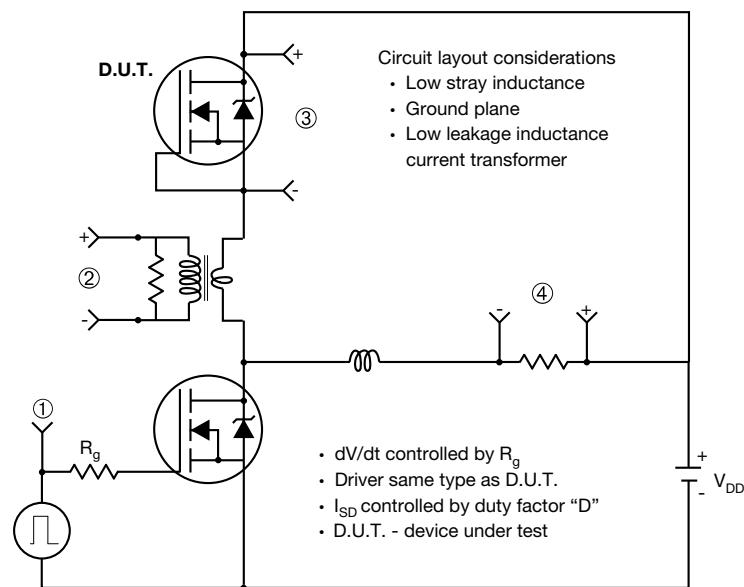


Fig. 15 - Unclamped Inductive Waveforms

Peak Diode Recovery dV/dt Test Circuit

Note

a. $V_{GS} = 5 \text{ V}$ for logic level devices

Fig. 18 - For N-Channel

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